

### Surface Mount Super fast Recovery Rectifier

Parameter	Value	Unit
$V_{RRM}$	50~600	V
$I_{F(AV)}$	2.0	A
$T_{RR}$	35	ns



DO-214AA/SMB

#### Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Super fast reverse recovery time

#### Applications

- For use in high-frequency rectification and free-wheeling applications in switching-mode converters and inverters for consumer electronics, computer systems, and telecommunications.

#### Absolute Maximum Ratings and Characteristics (Ta=25°C unless otherwise noted)

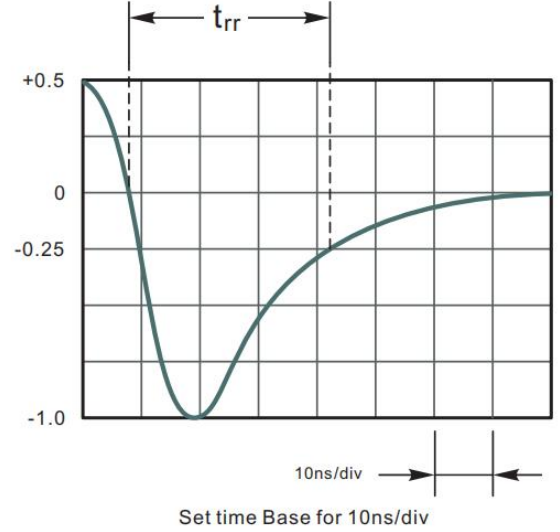
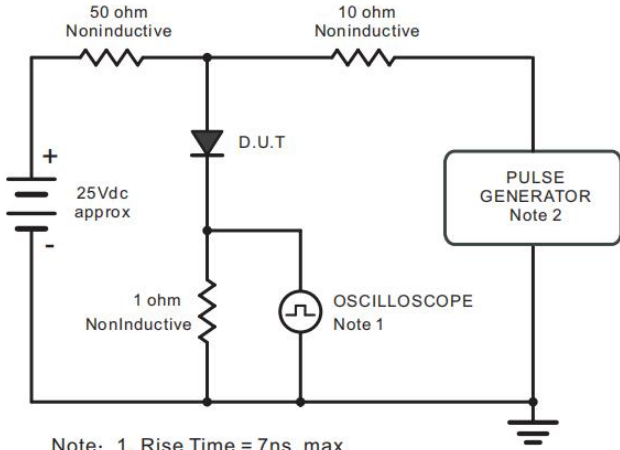
Parameter	Symbol	ES2AB	ES2BB	ES2CB	ES2DB	ES2EB	ES2GB	ES2JB	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_c = 125^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	60							A
Maximum Forward Voltage at 2A	$V_F$	1.0				1.25		1.68	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$					5			$\mu\text{A}$
						100			
Typical Junction Capacitance at $V_R=4\text{V}$ , $f=1\text{MHz}$	$C_j$	40							pF
Maximum Reverse Recovery Time (1)	$t_{rr}$	35							ns
Typical Thermal Resistance (2)	$R_{\theta JA}$	60							$^\circ\text{C/W}$
	$R_{\theta JC}$	20							
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150							$^\circ\text{C}$

#### Notes:

- (1) Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1\text{A}$ ,  $I_{rr} = 0.25\text{A}$ .  
 (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5cm) copper pad areas.

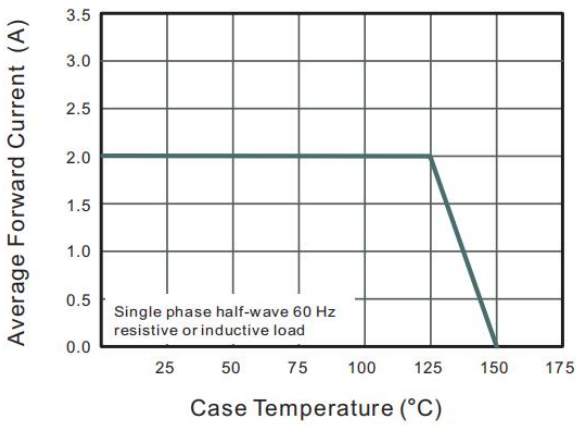
**Typical characteristics**

**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**

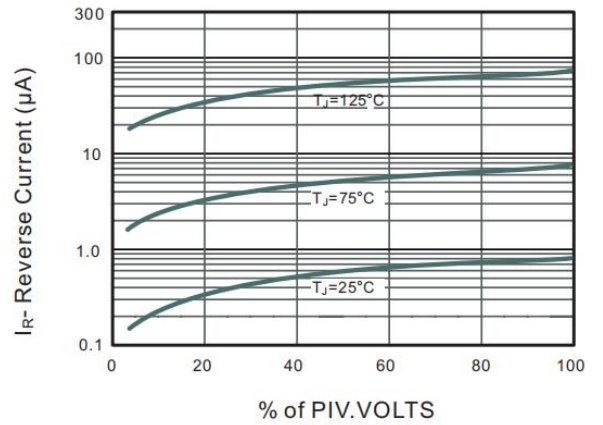


Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1 megohm, 22pF.  
2. Rises Time = 10ns, max.  
Source Impedance = 50 ohms.

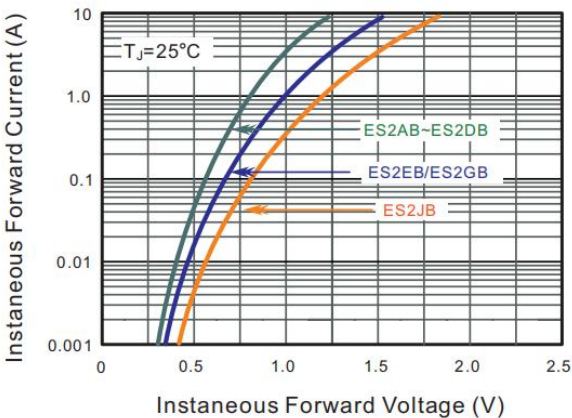
**Fig.2 Maximum Average Forward Current Rating**



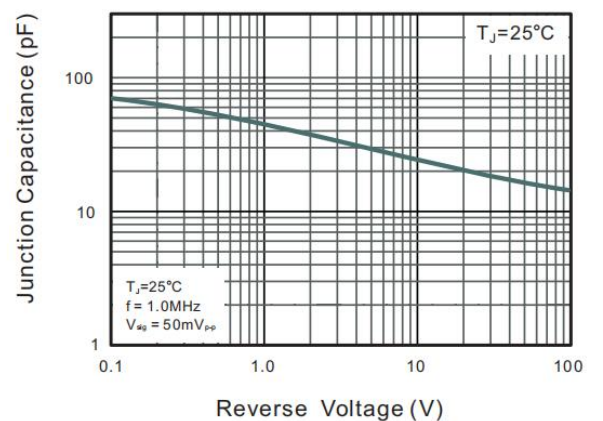
**Fig.3 Typical Reverse Characteristics**



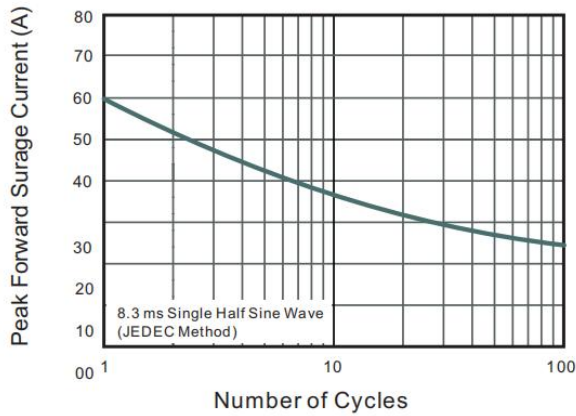
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



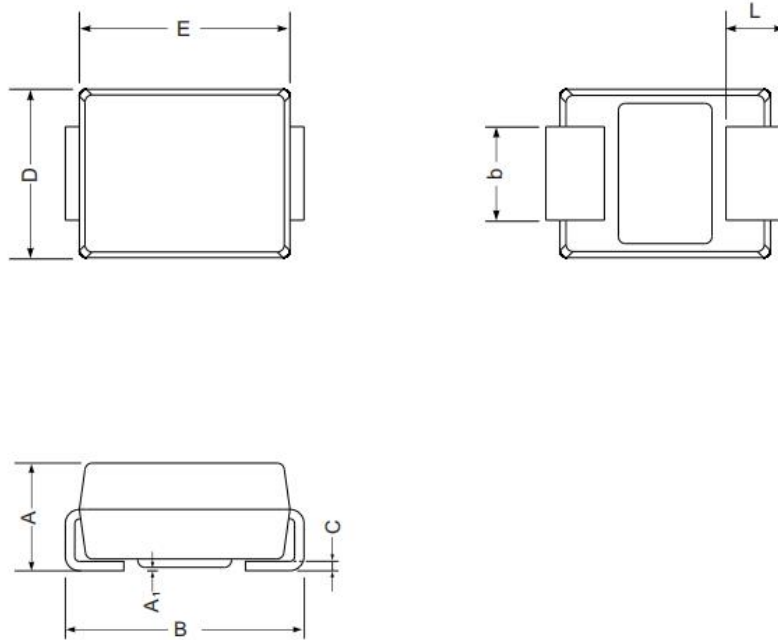
**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



**Package Outlines**

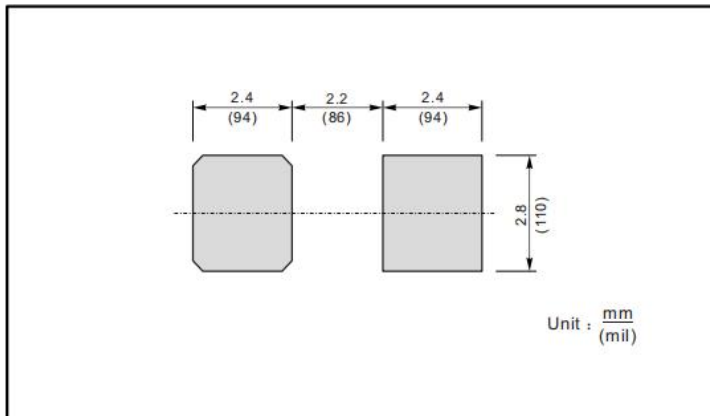
Plastic surface mounted package; 2 leads

**DO-214AA/SMB**



**SMB mechanical data**

UNIT		A	E	D	B	A <sub>1</sub>	L	C	b
mm	max	2.5	4.70	3.94	5.5	0.20	1.5	0.305	2.2
	min	2.1	4.06	3.3	5.0	0.05	0.8	0.152	1.9
mil	max	98	185	155	216	7.9	59	12	87
	min	82	160	130	196	2.0	32	6	75

**The recommended mounting pad size****Marking**

Type number	Marking code
ES2AB	ES2A
ES2BB	ES2B
ES2CB	ES2C
ES2DB	ES2D
ES2EB	ES2E
ES2GB	ES2G
ES2JB	ES2J

**\*Important Usage Information and Disclaimer**

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